

## Transfer-Printing of Prepatterned Semiconducting Few-Layer-Molybdenum Disulfide Structures for Electronic Applications

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Molybdenum disulfide ( $\text{MoS}_2$ ), previously widely used as a lubricant material, recently attracts a great deal of attention because of its attractive electronic, optoelectronic, and mechanical properties.<sup>1-3</sup> Especially, monolayer and few-layer  $\text{MoS}_2$  films have a large direct bandgap that is suitable for semiconductor-related applications such as thin-film transistors (TFTs)<sup>1</sup>, chemical sensors<sup>4</sup>, and light emission devices<sup>2</sup>. Such atomically layered films also exhibit a high mechanical flexibility and can be used for making flexible electronic products with high performance.<sup>3</sup> The current methods for producing few-layer  $\text{MoS}_2$  flakes include scotch tape exfoliation,<sup>5</sup> chemical vapor deposition (CVD),<sup>6</sup> and laser-thinning process<sup>7</sup> *etc.* These methods still suffer from specific disadvantages and cannot create ordered, pristine  $\text{MoS}_2$  device arrays over large areas that are required for large-area applications. Therefore, novel low-cost, upscalable nanofabrication methods are needed for addressing such manufacturing-related issues and enabling the future scale-up applications of  $\text{MoS}_2$  in electronics and optoelectronics. In this work, we systematically studied transfer-printing approaches for creating orderly arranged  $\text{MoS}_2$  micro- and nanostructures over large ( $\text{cm}^2$ -scale) areas and demonstrated working field-effect transistors (FETs) made from printed  $\text{MoS}_2$  flakes with excellent transistor performance. This research also identified the key processing conditions affecting the printing uniformity over large areas, morphologies of printed  $\text{MoS}_2$  structures, and ultimate transport properties of  $\text{MoS}_2$ -based FETs.

In our processes, the device patterns are firstly pre-structured onto a bulk  $\text{MoS}_2$  disc by using photolithography followed with plasma etching. This  $\text{MoS}_2$  disc is then used as a relief template for exfoliating prepatterned  $\text{MoS}_2$  flake arrays over large areas *via* various printing processes, including direct mechanical printing<sup>8</sup>, plasma-assisted printing, and electrostatic printing<sup>9</sup>. All of these printing processes can produce ordered  $\text{MoS}_2$  arrays over large areas, but different printing processes can result in different morphologies of individual  $\text{MoS}_2$  flakes, as demonstrated in Fig. 1. In addition, the  $\text{MoS}_2$  flakes created by various transfer-printing processes exhibit different transport properties. For example, Figs. 2a and 2b show  $I_{\text{DS}}-V_{\text{DS}}$  and  $I_{\text{DS}}-V_{\text{G}}$  characteristic curves, respectively, of a  $\text{MoS}_2$  FET produced by using electrostatic printing, which exhibit N-type conduction. Figure 2c shows the  $I_{\text{DS}}-V_{\text{G}}$  characteristic curve of another  $\text{MoS}_2$  FET made by plasma-assisted printing, which exhibits P-type conduction.

Our work demonstrated the printing of high-quality, well-defined  $\text{MoS}_2$  flakes over large areas and working  $\text{MoS}_2$ -based FETs with excellent performance. The fundamental knowledge achieved in this work could also be used for optimizing the printing-based manufacturing routes for producing other atomically layered materials and devices.

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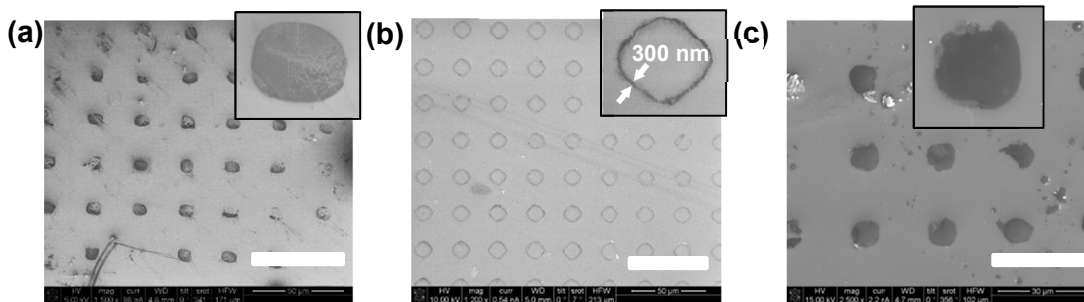


Fig. 1 SEMs of MoS<sub>2</sub> micro-/nanostructures produced by various transfer-printing processes: (a) microscale flakes with well-defined edges but broken central areas created by mechanical printing, (b) 300 nm wide rings with large-area uniformity created by plasma-assisted transfer-printing, and (c) microscale flakes with continuous MoS<sub>2</sub> films created by electrostatic printing. All the scale bars are 50  $\mu$ m.

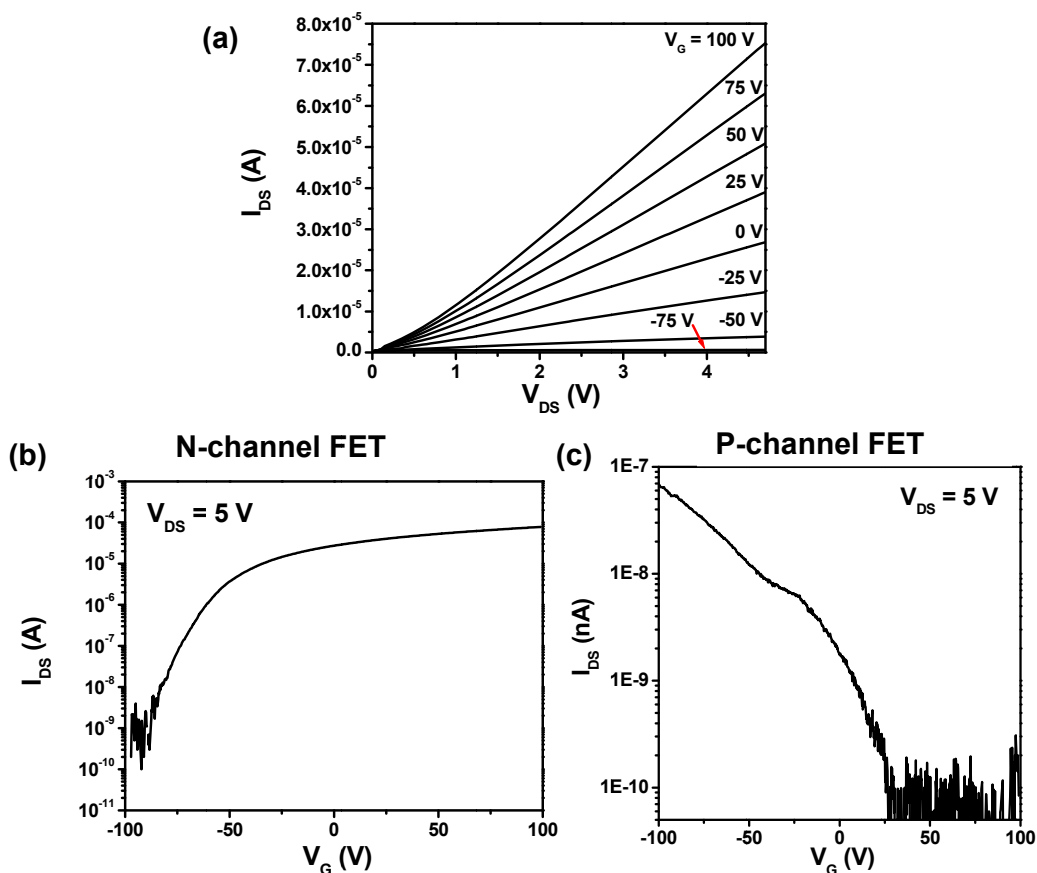


Fig. 2 Transport characteristics of MoS<sub>2</sub>-based FETs made from transfer-printed MoS<sub>2</sub> flakes. (a)  $I_{DS}$ - $V_{DS}$  and (b)  $I_{DS}$ - $V_G$  characteristic curves of an N-channel MoS<sub>2</sub> FET; (c)  $I_{DS}$ - $V_G$  characteristic curve of a P-channel MoS<sub>2</sub> FET made by using plasma-assisted transfer-printing.